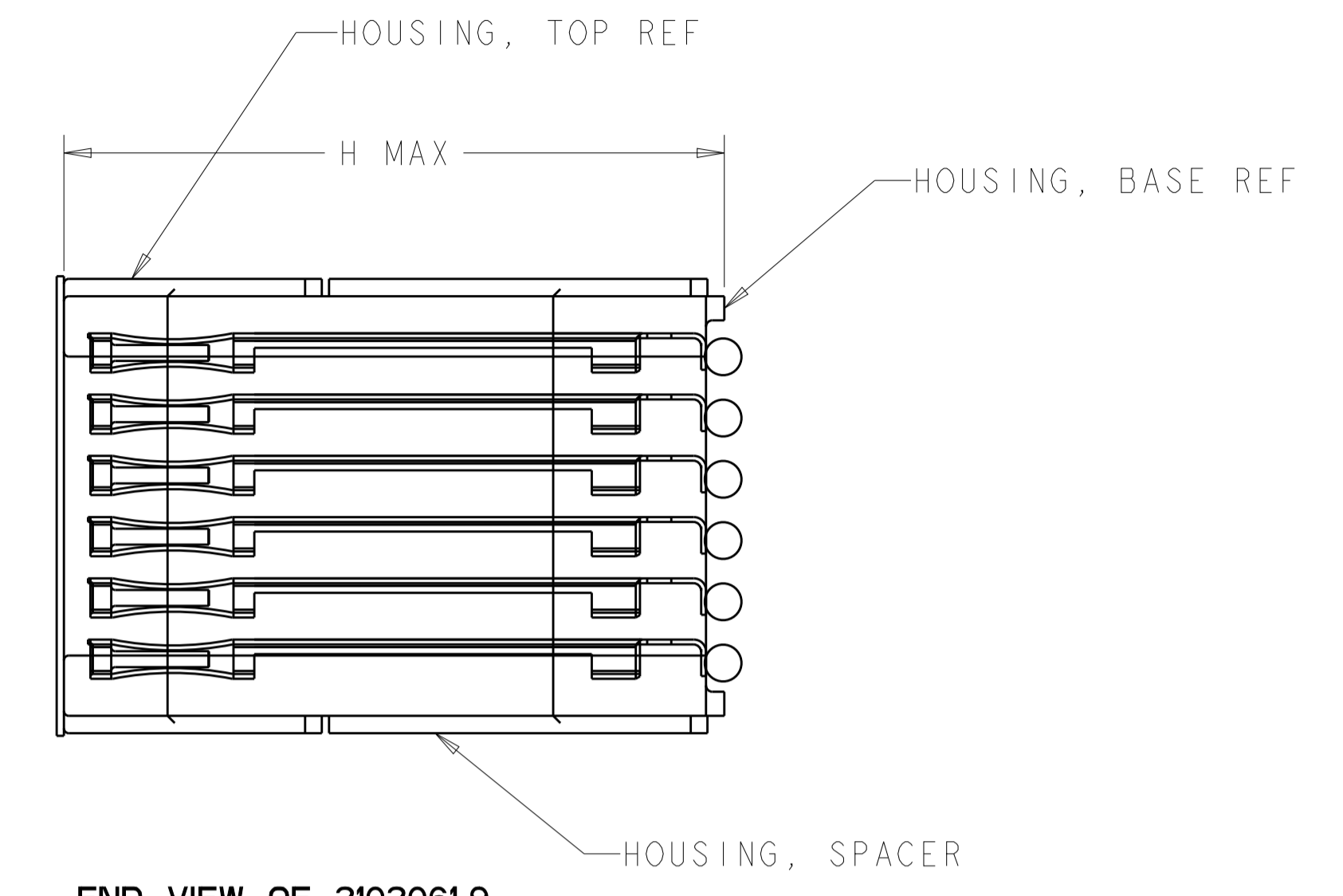
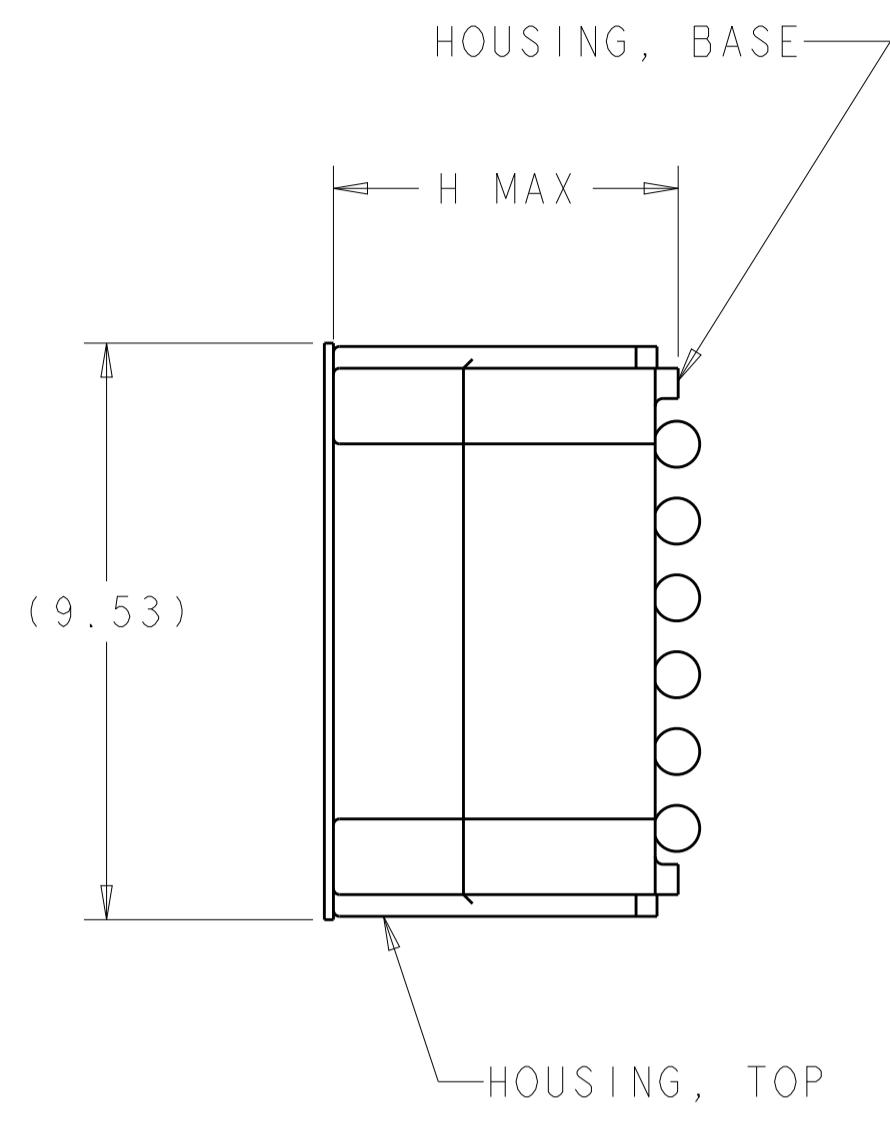
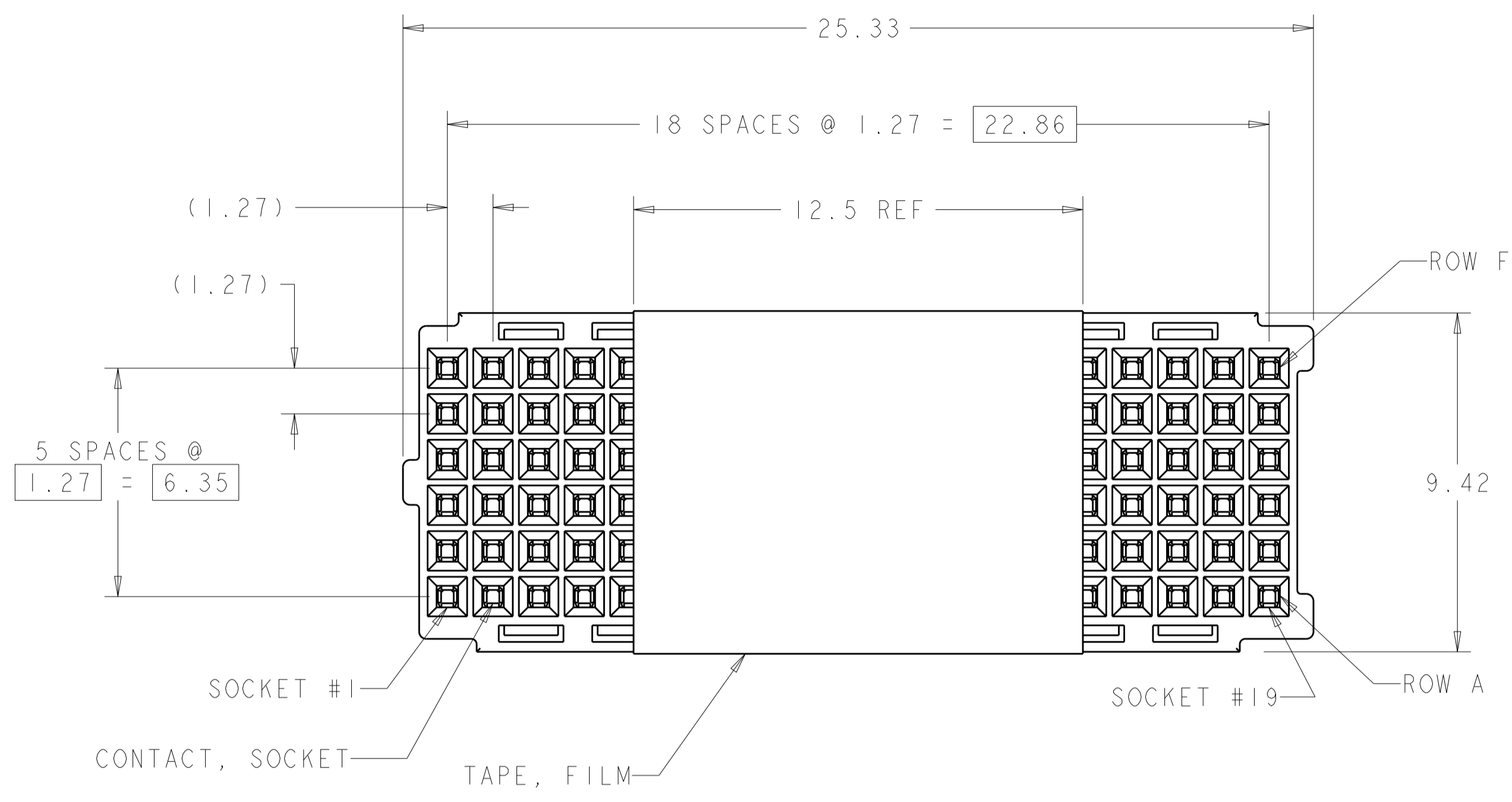
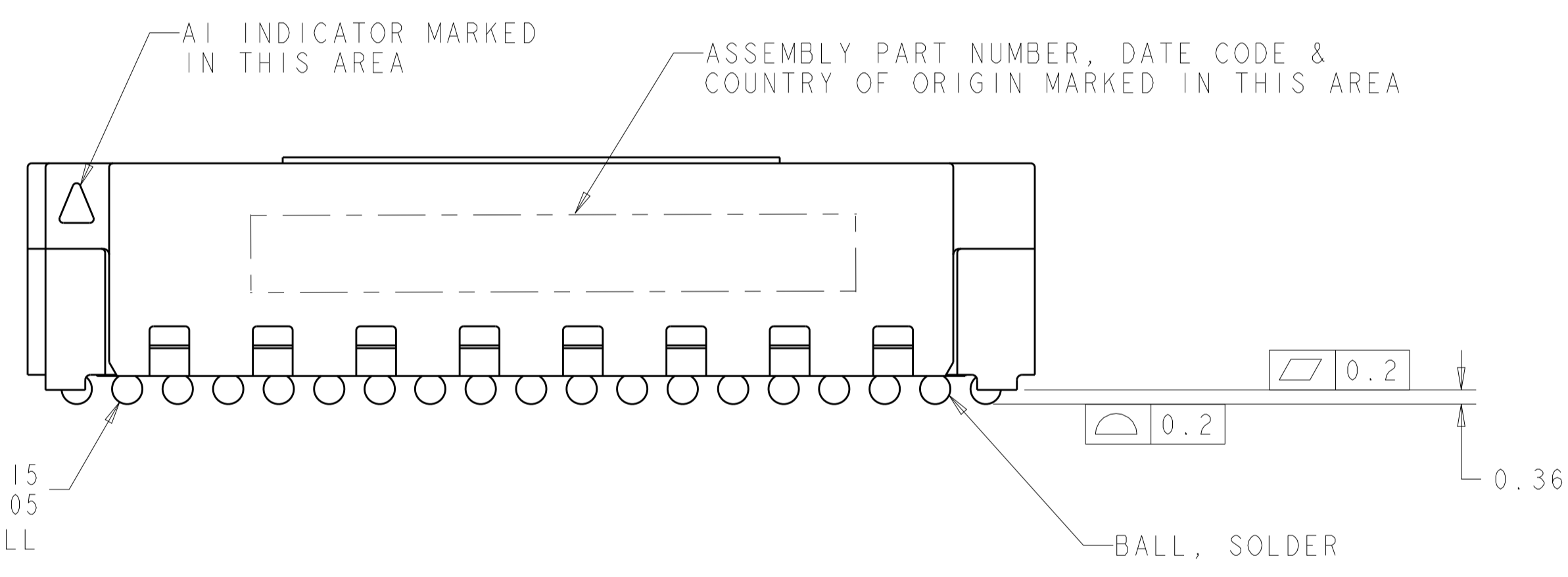


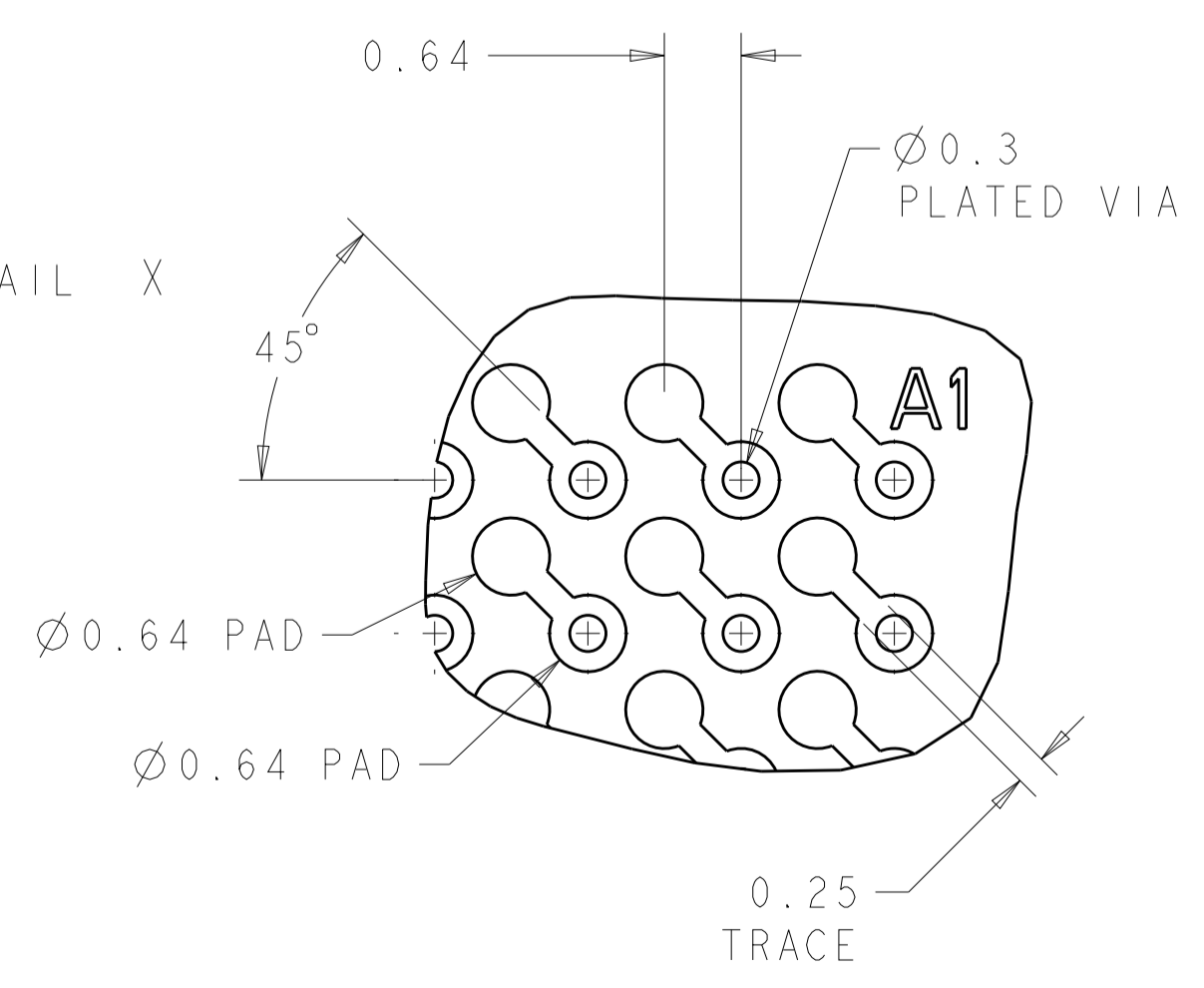
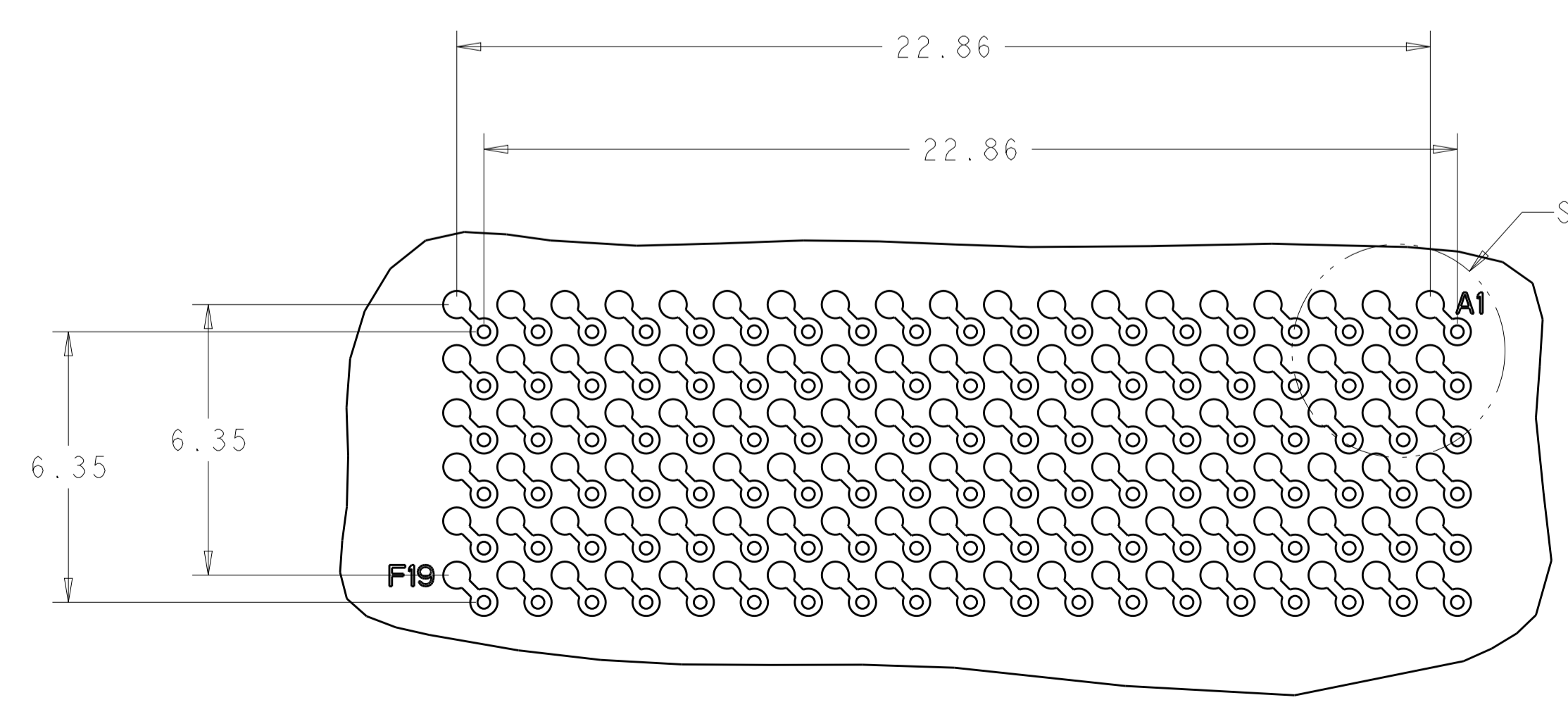
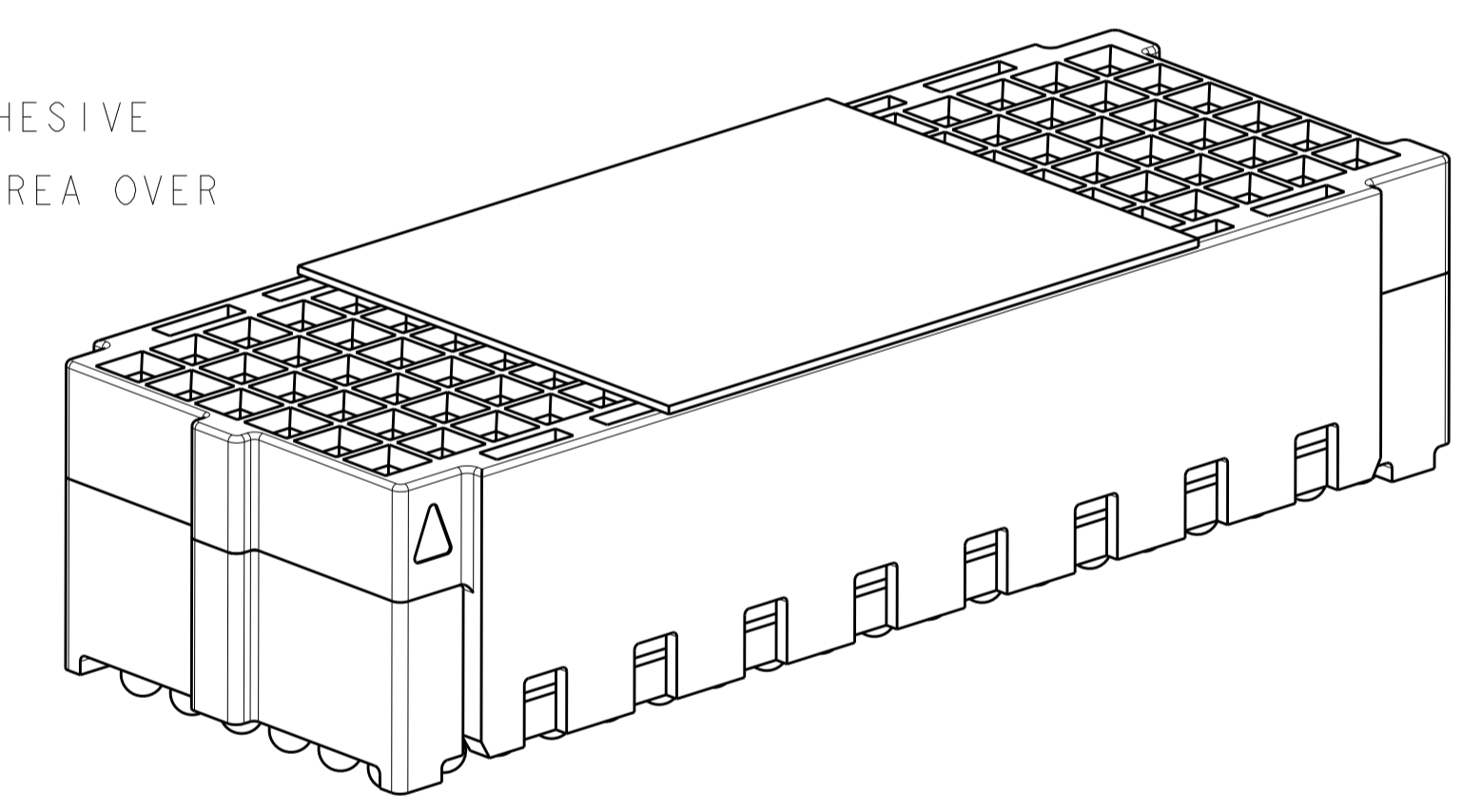
LOC		DIST		REVISIONS			
P	LTN	DESCRIPTION	DATE	DWN	APVD		
F		REV PER ECO 12-021576	12-18-12	CT	DH		



END VIEW OF 2102061-9 THRU 1-2102061-6



- △ MATERIAL: HOUSINGS; LCP, COLOR-NATURAL CONTACT; BERYLLIUM COPPER SOLDER BALL; SEE TABLE TAPE, FILM; KAPTON WITH SILICON ADHESIVE
- △ FINISH: CONTACT; GOLD (SEE TABLE) ON MATING AREA OVER NICKEL ON ENTIRE CONTACT.
- 3. PRODUCT IS PACKAGED ON TAPE AND REELED.
- △ PRELIMINARY- NOT RELEASED FOR PRODUCTION



MATING PART NUMBER	MATED STACK HEIGHT (mm)	GOLD PLATING THICKNESS	H MAX REF	SOLDER BALL MATERIAL	PART NUMBER
2102060-4	15	0.76 μ m	11	LEAD FREE PER SAC405	1-2102061-6
2102060-3	15	0.76 μ m	11	TIN LEAD	1-2102061-5
2102060-2	15	1.27 μ m	11	LEAD FREE PER SAC405	1-2102061-4
2102060-1	15	1.27 μ m	11	TIN LEAD	1-2102061-3
2102060-4	18	0.76 μ m	14	LEAD FREE PER SAC405	1-2102061-2
2102060-3	18	0.76 μ m	14	TIN LEAD	1-2102061-1
2102060-2	18	1.27 μ m	14	LEAD FREE PER SAC405	1-2102061-0
2102060-1	18	1.27 μ m	14	TIN LEAD	2102061-9
2102060-4	12	0.76 μ m	8	LEAD FREE PER SAC405	2102061-8
2102060-3	12	0.76 μ m	8	TIN LEAD	2102061-7
2102060-4	10	0.76 μ m	6	LEAD FREE PER SAC405	2102061-6
2102060-3	10	0.76 μ m	6	TIN LEAD	2102061-5
2102060-2	12	1.27 μ m	8	LEAD FREE PER SAC405	2102061-4
2102060-1	12	1.27 μ m	8	TIN LEAD	2102061-3
2102060-2	10	1.27 μ m	6	LEAD FREE PER SAC405	2102061-2
2102060-1	10	1.27 μ m	6	TIN LEAD	2102061-1

PCB LAYOUT (CONNECTOR SIDE) SCALE 8:1

DETAIL X SCALE 16:1

THIS DRAWING IS A CONTROLLED DOCUMENT. DWG: G. DOUTY 23JUL2009. CHK: K. DOWHOWER 23JUL2009. APVD: K. DOWHOWER 23JUL2009.

DIMENSIONS: mm. TOLERANCES UNLESS OTHERWISE SPECIFIED: 0 PLC \pm , 1 PLC ± 0.13 , 2 PLC \pm , 3 PLC \pm , 4 PLC \pm , ANGLES \pm .

MATERIAL: FINISH: CUSTOMER DRAWING.

STE TE Connectivity. NAME: ASSEMBLY, SOCKET, 114 POSITION, MEZALOK STACKING CONNECTOR. SIZE: 108-2411. APPLICATION SPEC: 114-13279. WEIGHT: A100779. SCALE: 8:1. SHEET 1 OF 1. REV F.